

**ASSIGNMENT RECORDATION COVER SHEET
-PATENTS ONLY-**

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document(s) or copy thereof.

1. Name of conveying party(ies)
a) Daniel Wayne Bedell
b) Richard Hsiao
c) James D. Jarratt
d) Patrick Rush Webb
e) Sue Siyang Zhang
2. Name and address of receiving party(ies):
a) Name: Hitachi Global Storage Technologies Netherlands B.V.
Address: Locatellikade 1
1076 AZ Amsterdam
P.O. Box 75215
1070 AE Amsterdam
The Netherlands
3. Nature of conveyance
☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____ ☐ License Agreement

Execution Date: October 7, 2003, October 7, 2003, October 7, 2003, October 6, 2003 and October 6, 2003

4. Application Number(s) or Patent Number(s): 11/040,387

The title of the (new) application is:

**MAGNETIC HEAD COIL SYSTEM AND DAMASCENE/REACTIVE ION
ETCHING METHOD FOR MANUFACTURING THE SAME**

5. Please send all correspondence concerning this (these) documents to:

Zilka-Kotab, PC
P.O. Box 721120
San Jose, California 95172-1120


6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41):
- \$40.00

- ☐
- Enclosed
-
- ☒
- Authorized to be charged to Deposit Account No. 50-2587 (Order No.
- HSJ920030045US2
-)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date:

4/22/05

Dominic M. Kotab
Registration No. 42,762

COPY

ASSIGNMENT OF PATENT APPLICATION
(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:


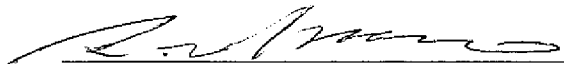
MAGNETIC HEAD COIL SYSTEM AND DAMASCENE/REACTIVE ION
ETCHING METHOD FOR MANUFACTURING THE SAME

(Atty. Docket No.: HIT1P006/HSJ920030045US1) for which I (we) have executed an application for a United States Letters Patent.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I/we the undersigned inventor(s) hereby:

- 1) Sell(s), assign(s) and transfer(s) to Hitachi Global Storage Technologies Netherlands B.V., a corporation having a place of business at Locatellikade 1, 1076 AZ Amsterdam, P.O. Box 75215, 1070 AE Amsterdam, The Netherlands, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application(s) based upon, and Patent(s) (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division(s), continuation(s), substitutes(s) or reissue(s) thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the Assignee, its successors, assigns and other legal representative, and shall be binding upon the inventor(s), as well as the inventor's heirs, legal representatives and assigns.
- 5) Warrant and represent that I/we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the date(s) indicated beside my (our) signature(s).

- 1) Signature:  Date: 10/7/03
Typed Name: Daniel Wayne Bedell
- 2) Signature:  Date: 10/7/2003
Typed Name: Richard Hsiao

- 3) Signature: _____ Date: _____
Typed Name: James D. Jarratt
- 4) Signature: Patrick Rush Webb Date: 10/6/03
Typed Name: Patrick Rush Webb
- 5) Signature: Sue Siyang Zhang Date: 10/6/03
Typed Name: Sue Siyang Zhang

COPY

ASSIGNMENT OF PATENT APPLICATION
(Accompanying Application)

Whereas I/we the undersigned inventor(s) have invented certain new and useful improvements as set forth in the patent application entitled:

MAGNETIC HEAD COIL SYSTEM AND DAMASCENE/REACTIVE ION
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- 1) Signature: _____ Date: _____
Typed Name: Daniel Wayne Bedell
- 2) Signature: _____ Date: _____
Typed Name: Richard Hsiao

- 3) Signature: James D. Jarratt Date: 10/7/03
Typed Name: James D. Jarratt
- 4) Signature: _____ Date: _____
Typed Name: Patrick Rush Webb
- 5) Signature: _____ Date: _____
Typed Name: Sue Siyang Zhang